

An IATF 16949, ISO9001 and ISO 14001/ISO 45001 Certified Company





## Single Phase Silicon Bridge Rectifier

Reverse voltage - 50 to 1000Volts, Forward current - 4A.



KBI



**KBL005 ~ KBL10** 

Package: KBL Leaded Plastic Package RoHS compliant

## **FEATURES:**

- 1. Surge overload rating -125 Amperes peak
- 2. Ideal for printed circuit board
- 3. Plastic material has UL flammability classification 94V-0
- 4. Mounting position :Any
- 5. Weight: 0.18 ounces, 4.7 grams
- 6. Glass passivated chip
- 7. This product is available in AEC-Q101 Compliant and PPAP Capable also.

Note: For AEC-Q101 compliant products, please use suffix -AQ in the part number while ordering

## ABSOLUTE MAXIMUM RATINGS ELECTRICALCHARACTERISTICS

Rating at  $25^{\circ}$ C ambient temperature unless otherwise specified. Single phase, half wave ,60Hz, resistive or inductive load. For capacitive load, derate current by 20%

PARAMETERS	SYMBOL	KBL 005	KBL 01	KBL 02	KBL 04	KBL 06	KBL 08	KBL 10	UNIT
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS Bridge Input Voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward Output Current at T <sub>A</sub> 50 °C <sup>1</sup>	I <sub>(AV)</sub>	4.0				Α			
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load	I <sub>FSM</sub>	125				Α			
Maximum Forward Voltage Drop Per Element at 4.0A Peak	V <sub>F</sub>	1.1				V			
Maximum DC Reverse Current at Rated DC Blocking Voltage	I <sub>R</sub>	10.0				μA			
Maximum Reverse Current at Rated DC Blocking Voltage and T <sub>A</sub> 150°C	I <sub>R</sub>	1.0			mA				
Operating Temperature Range	$T_J$	-55 to +150		°C					
Storage Temperature Range	$T_{STG}$	-55 to +150			C				

**Notes:** 1. Mounting conditions ,0.5" lead length maximum.

KBL005-KBL10

Rev1 05042024SW/FZ







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**Typical Characteristic curves**Fig 1: MAXIMUM FORWARD CURRENT DERATING CURVE

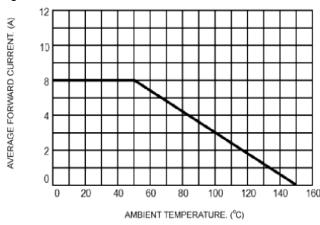


Fig 4:TYPICAL JUNTION CAPACITANCE

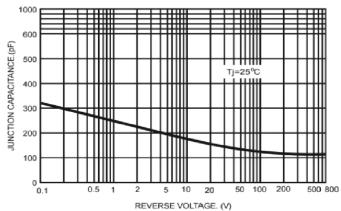


Fig 2:Typical Reverse Characteristics per Bridge Element

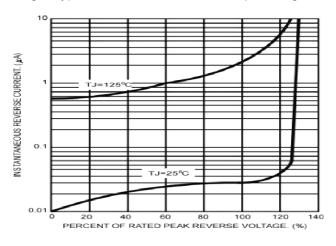


Fig 4:TYPICAL INSTANTANOUS FORWARD CHARACTERISTICS PER BRIDGE ELEMENT

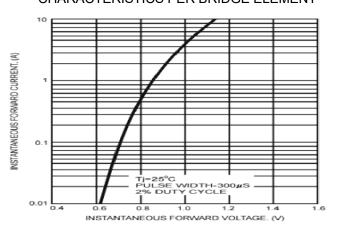
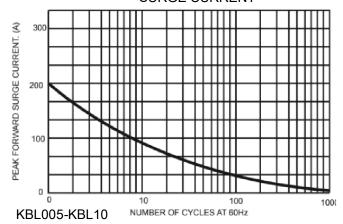


Fig 3: MAXIMUM NON REPETITIVE PEAK FORWARD SURGE CURRENT



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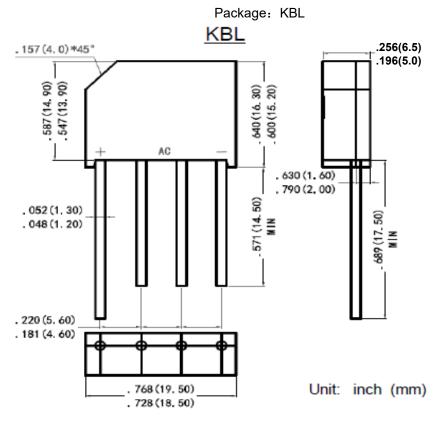






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## **Package Details**









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## **Recommended Reflow Solder Profiles**

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.

Figure 1

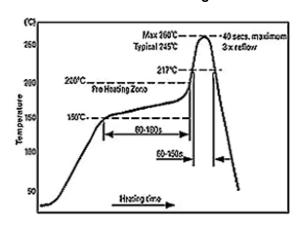
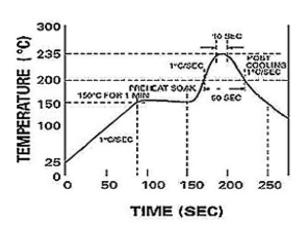


Figure 2



## Reflow profiles in tabular form

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Profile Feature	Sn-Pb System	Pb-Free System			
Average Ramp-Up Rate	~3°C/second	~3°C/second			
Preheat  – Temperature Range  – Time	150-170°C 60-180 seconds	150-200°C 60-180 seconds			
Time maintained above:  – Temperature  – Time	200°C 30-50 seconds	217°C 60-150 seconds			
Peak Temperature	235°C	260°C max.			
Time within +0 -5°C of actual Peak	10 seconds	40 seconds			
Ramp-Down Rate	3°C/second max.	6°C/second max.			



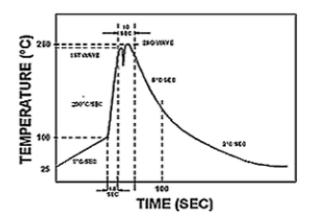




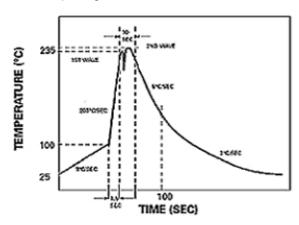
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## **Recommended Wave Solder Profiles**

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used



The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder



#### **Wave Profiles in Tabular Form**

Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~200°C/second	~200°C/second
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	10 seconds
Ramp-Down Rate	5°C/second max.	5°C/second max







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# Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- · Temperature 5 °C to 30 °C
- · Humidity between 40 to 70 %RH
- · Air should be clean.
- · Avoid harmful gas or dust.
- · Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- · Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- · Avoid condensation.
- · Mechanical stress such as vibration and impact shall be avoided.
- · The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

#### **Shelf Life of CDIL Products**

The shelf life of products is the period from product manufacture to shipment to customers. The product can

## Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start.

For this, the following JEDEC table may be referred:

JEDEC MSL Level				
Level	Time	Condition		
1	Unlimited	≤30 °C / 85% RH		
2	1 Year	≤30 °C / 60% RH		
2a	4 Weeks	≤30 °C / 60% RH		
3	168 Hours	≤30 °C / 60% RH		
4	72 Hours	≤30 °C / 60% RH		
5	48 Hours	≤30 °C / 60% RH		
5a	24 Hours	≤30 °C / 60% RH		
6	Time on Label(TOL)	≤30 °C / 60% RH		







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#### **Customer Notes**

## **Component Disposal Instructions**

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

### Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



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